

ABSTRACT

The present invention provides methods for fabricating bond pads that can be employed for fabricating solder bumps and wire bonds, as well as structures containing
5 the bond pads. Bond pads of the present invention include a contiguous interconnect line, fabricated in a dielectric layer such that the bond pad and line are exposed. A passivation layer is then deposited on the dielectric layer, the bond pad and the interconnect line. A passivation hole is etched in the passivation layer such that the hole exposes at least a portion of the bond pad. The bond pad and contiguous interconnect line can be provided
10 with a metal overcoat layer on the top surface of the bond pad, and a barrier/seed layer on the bottom and side surfaces of the bond pad and the contiguous interconnect line.